**EPC9166** 12 V Input, 48 V/500 W Output Dual Phase Synchronous Boost Converter Evaluation Board Quick Start Guide

Using EPC2218 Enhancement Mode eGaN<sup>®</sup> FET

November 9, 2021

Version 1.0



# DESCRIPTION

The EPC9166 is a 500 W 12 V to 48 V synchronous Boost converter using eGaN® FET. EPC9166 is designed with **EPC2218** enhancement mode eGaN® FET and ISL81807 two phase analog boost controller with integrated eGaN drivers. EPC9166 main features:

- High efficiency: >96.5% with 12 V input and 48 V output
- Switching frequency: 500 kHz
- Reconfigurable output voltage: 36 V, 48 V, 60 V
- Analog controller with integrated gate driver optimized for eGaN<sup>®</sup> FET
- Other functions:
  - o Soft start
  - o UVLO
  - o Over-current protection
  - o Power good output

#### Terrers. Terres

EPC9166 board

## **REGULATORY INFORMATION**

This power module is for evaluation purposes only. It is not a full-featured power module and cannot be used in final products. No EMI test was conducted. It is not FCC approved.

#### Table 1: Electrical Characteristics ( $T_A = 25^{\circ}C$ )

Symbol	Parameter	Conditions	Min	Тур	Мах	Units
V <sub>IN</sub>	Input voltage		9	12	28	
V <sub>UV,Rise</sub>	Input UVLO turn on voltage, rising edge			8.3		
V <sub>UV,Fall</sub>	Input UVLO turn on voltage, falling edge			7.5		
V <sub>OUT</sub>	Output voltage		36	48	60	
ΔV <sub>OUT</sub>	Output voltage ripple	Peak to peak			500	mV
		$V_{IN} = 12 V, V_{OUT} = 36 V$			16 <sup>[1]</sup>	
I <sub>OUT</sub>	Output Current	$V_{IN} = 12 V, V_{OUT} = 48 V$			11 <sup>[1]</sup>	A
		$V_{IN} = 12 V, V_{OUT} = 60 V$			8 <sup>[1]</sup>	
f <sub>s</sub>	Switching frequency	Mode = CCM		490		kHz

<sup>[1]</sup> The maximum current capability is dependent on thermal conditions. The maximum current shown here is for 1000 LFM or greater. If testing with less than 1000 LFM cooling, the FET temperature should be monitored to ensure the maximum temperature does not exceed the rating in the datasheet.



EPC – POWER CONVERSION TECHNOLOGY LEADER | EPC-CO.COM | ©2021 | For more info: info@epc-co.com

# **CUSTOM CIRCUIT CONFIGURATIONS**

#### **Output voltage settings**

The EPC9166 output voltage can be configured by table 2.

#### Table 2: Output voltage settings

Output Voltage	J6	J7
60 V	Open	Open
48 V (default)	Install	Open
36 V	Open	Install

## **QUICK START PROCEDURE**

The evaluation board EPC9166 is easy to set up to evaluate the performance of the EPC2218 eGaN FETs and directly drive from the controller IC. Refer to figure 1 for proper connect and measurement setup and follow the procedure below:

- 1. Configure the jumpers for phase mode the output voltage setting per figure 1 and table 2. The phase mode jumper J8 sets the 180° phase shift between the two phases in its default location (1). The output voltage is set by jumper J6 and J7 and the default location (2) sets the output voltage at 48 V.
- 2. With power off, connect the input power supply between VIN (J3) and GND (J18). A shunt can be inserted to measure input current.
- 3. With power off, connect a programmable load as needed between VOUT (J4) and GND (J5) as shown in figure 1.
- 4. Turn on the supply voltage to 12 V and keep the load OFF. The converter will not start up until the input voltage is above 9 V. The converter is not designed to start up with large load.
- 5. Check the output voltage is regulated to 48 V to make sure the board is functional. If 48 V is not observed, please carefully re-examine the circuit connections.
- 6. Activate the programmable load and set to the desired current ensuring the maximum current does not exceed the maximum ratings.
- 7. Once operational, adjust the bus voltage and load current within the allowed operating range and observe the output switching behavior. For measuring switch node waveforms, please use probes without ground lead and measure as close to the FET. An unpopulated two pin connecter is designed for easy measurement. Please note polarity.
- 8. For shutdown, please follow steps in reverse. For custom configuration please refer the custom configuration section.



# **ELECTRICAL PERFORMANCE**

Typical efficiency and power loss







#### Typical output voltage ripple



#### Typical soft start waveforms



#### **Typical transient response**



 $V_{IN} = 12 V, V_{OUT} = 48 V$ , output 5 A to 10 A, di/dt = 2 A/us



**Typical load regulation** 

# QUICK START GUIDE

## Typical switch node waveform



Figure 7(a): Typical switch node waveform (rising edge):  $V_{IN} = 12 V$ ,  $V_{OUT} = 48 V$ ,  $I_{OUT} = 5 A$ 



Figure 7(b): Typical switch node waveform (falling edge):  $V_{\rm IN} = 12$  V,  $V_{\rm OUT} = 48$  V,  $I_{\rm OUT} = 5$  A

### Typical thermal performance



Figure 8: Typical thermal performance:  $V_{\rm IN} =$  12 V,  $V_{\rm OUT} =$  48 V,  $I_{\rm OUT} =$  10 A, 400 LFM air flow

(3)

#### Input UVLO adjustment

The input UVLO threshold voltage can be set by R6 and R7 as shown in Figure 9. The default values of Vuv are listed in table 1. If needed, a new UVLO voltage and hysteresis can be set by changing R6 and R7 using equation (1) and (2). Please refer to ISL81807 datasheet for more information.

$$V_{\text{uvrise}} = \frac{1.8(\text{R6} + \text{R7}) - 2.8 \times 10^{-6} \text{ R6R7}}{\text{R7}}$$
(1)

$$V_{\rm uvfall} = \frac{1.8(R6 + R7) - 6.8 \times 10^{-6} \, R6R7}{R7}$$
(2)



Figure 9: EPC9166 ULVO settings: location of R6 & R7

#### Switching frequency adjustment

The switching frequency is set by the value of R35 with the frequency given in equation (3). The default frequency is 500 kHz. The location of R35 is shown in Fig 10. Refer to ISL81807 datasheet for more information.

$$f_s (MHz) \approx \frac{34 (MHz)}{R35 (k\Omega)}$$



Figure 10: EPC9166 frequency setting: location of R35

# THERMAL MANAGEMENT (Optional)

The EPC9166 is intended for bench evaluation at room ambient temperatures and under forced air convection cooling. The addition of heatsink along with forced air cooling is not required but can significantly improve the heat dissipation from the FETs from the top side and increase the current capacity of these devices. A TIM is required between the FETs and the heatsink. The choice of TIM needs to consider the following characteristics:

The EPC9166 board is equipped with four mechanical spacers (S1, S2, S3, S4) that can be used to easily attach a standard eighth-brick converter heatsink as shown in figure 11, and only requires a thermal interface material (TIM), a heatsink, and screws.



Figure 11: Exploded 3D assembly of heat sink installment (a) and dimensions and locations of TIM material (b)

The following heat sink is recommended for EPC9166:

Wakefield P/N:567-45AB

A TIM is required between the FETs and the heatsink. The choice of TIM needs to consider the following characteristics:

- **Mechanical compliance** During the attachment of the heat spreader, the TIM underneath is compressed from its original thickness to the vertical gap distance between the spacers and the FETs. This volume compression exerts a force on the FETs. A maximum compression of 2:1 is recommended for maximum thermal performance and to constrain the mechanical force which maximizes thermal mechanical reliability.
- Electrical insulation The backside of the eGaN FET is a silicon substrate that is connected to source and thus the upper FET in a half-bridge configuration is connected to the switch-node. To prevent short-circuiting the switch-node to the grounded thermal solution, the TIM must be of high dielectric strength to provide adequate electrical insulation in addition to its thermal properties.
- **Thermal performance** The choice of thermal interface material will affect the thermal performance of the thermal solution. Higher thermal conductivity materials is preferred to provide higher thermal conductance at the interface.

EPC recommends the following thermal interface materials (TIM) for EPC9166:

- t-Global P/N: TG-A1780 X 0.5 mm (highest conductivity of 17.8 W/m·K)
- t-Global P/N: TG-A620 X 0.5 mm (moderate conductivity of 6.2 W/m·K)

**NOTE**. The EPC9166 evaluation board does not have any current or thermal protection on board. For more information regarding the thermal performance of EPC eGaN FETs, please consult: D. Reusch and J. Glaser, *DC-DC Converter Handbook, a supplement to GaN Transistors for Efficient Power Conversion,* First Edition, Power Conversion Publications, 2015.

# **MECHANICAL SPECIFICATIONS**



# For More Information:

Please contact **info@epc-co.com** or your local sales representative

Visit our website: www.epc-co.com

Sign-up to receive EPC updates at **bit.ly/EPCupdates** 



DigiKey

EPC Products are distributed through Digi-Key. www.digikey.com

#### **Evaluation Board Notification**

The EPC9166 board is intended for product evaluation purposes only. It is not intended for commercial use nor is it FCC approved for resale. Replace components on the Evaluation Board only with those parts shown on the parts list (or Bill of Materials) in the Quick Start Guide. Contact an authorized EPC representative with any questions. This board is intended to be used by certified professionals, in a lab environment, following proper safety procedures. Use at your own risk.

As an evaluation tool, this board is not designed for compliance with the European Union directive on electromagnetic compatibility or any other such directives or regulations. As board builds are at times subject to product availability, it is possible that boards may contain components or assembly materials that are not RoHS compliant. Efficient Power Conversion Corporation (EPC) makes no guarantee that the purchased board is 100% RoHS compliant.

The Evaluation board (or kit) is for demonstration purposes only and neither the Board nor this Quick Start Guide constitute a sales contract or create any kind of warranty, whether express or implied, as to the applications or products involved.

Disclaimer: EPC reserves the right at any time, without notice, to make changes to any products described herein to improve reliability, function, or design. EPC does not assume any liability arising out of the application or use of any product or circuit described herein; neither does it convey any license under its patent rights, or other intellectual property whatsoever, nor the rights of others.